

Title (en)

PRINTABLE MEDIUM FOR THE ETCHING OF SILICON DIOXIDE AND SILICON NITRIDE LAYERS

Title (de)

DRUCKF[HIGES MEDIUM ZUR ÄTZUNG VON SILIZIUMDIOXID- UND SILIZIUMNITRIDSCHICHTEN

Title (fr)

AGENT POUVANT ETRE APPLIQUE PAR IMPRESSION POUR L'ATTAQUE DE COUCHES DE DIOXYDE DE SILICIUM ET DE NITRURE DE SILICIUM

Publication

EP 1838639 A1 20071003 (DE)

Application

EP 05818404 A 20051219

Priority

- EP 2005013657 W 20051219
- DE 102005001343 A 20050111
- DE 102005007743 A 20050218

Abstract (en)

[origin: WO2006074791A1] The invention relates to a novel printable etching medium, with non-Newtonian flow properties for the etching of surfaces in the production of solar cells and the use thereof. The invention particularly relates to corresponding particle-containing compositions, by means of which the very selective fine structures can be etched without damaging or attacking adjacent surfaces.

IPC 8 full level

C03C 15/00 (2006.01)

CPC (source: EP KR US)

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Citation (search report)

See references of WO 2006074791A1

Citation (examination)

WO 2005050673 A1 20050602 - MERCK PATENT GMBH [DE], et al

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DOCDB simple family (publication)

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